PD IEC/TS 62878-2-3:2015

BSI Standards Publication

Device embedded substrate

Part 2-3: Guidelines — Design guide

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colour inside

Device embedded substrate – Part 2-3: Guidelines – Design guide

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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DEVICE EMBEDDED SUBSTRATE –

Part 2-3: Guidelines – Design guide

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Technical Specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC TS 62878-2-3, which is a Technical Specification, has been prepared by IEC technical committee 91: Electronics assembly technology.

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The text of this Technical Specification is based on the following documents:

Enquiry draft	Report on voting
91/1143/DTS	91/1164A/RVC

Full information on the voting for the approval of this Technical Specification can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62878 series, published under the general title *Device embedded substrate*, can be found on the IEC website.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

This part of IEC 62878 provides guidance with respect to device embedded substrate, fabricated by embedding discrete active and passive electronic devices into one or multiple inner layers of a substrate with electric connections by means of vias, conductor plating, conductive paste, and printing. Within the IEC 62878 series,

- IEC 62878-1-1 specifies the test methods,
- IEC TS 62878-2-1 gives a general description of the technology,
- IEC TS 62878-2-3, provides guidance on design, and
- IEC TS 62878-2-4 specifies the test element groups.

The device embedded substrate may be used as a substrate to mount SMDs to form electronic circuits, as conductor and insulator layers may be formed after embedding electronic devices.

The purpose of the IEC 62878 series is to achieve a common understanding with respect to structures, test methods, design and fabrication processes and the use of the device embedded substrate in industry.

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DEVICE EMBEDDED SUBSTRATE –

Part 2-3: Guidelines – Design guide

1 Scope

This part of IEC 62878 describes the design guide of device embedded substrates.

The design guide of device embedded substrate is essentially the same as that of various electronic circuit boards. This part of IEC 62878 enables a thorough understanding of circuit design, structure design, board design, board manufacturing, jisso (assembly processes) and tests of products.

This part of IEC 62878 is applicable to device embedded substrates fabricated by use of organic base material, which include for example active or passive devices, discrete components formed in the fabrication process of electronic wiring board, and sheet formed components.

The IEC 62878 series neither applies to the re-distribution layer (RDL) nor to the electronic modules defined as an M-type business model in IEC 62421.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

3 Terms, definition and abbreviations

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

3.2 Abbreviations

AABUS	as agreed between user and supplier
BGA	ball grid array
IPD	integrated passive device
LGA	land grid array
LSI	large scale integration
MEMS	micro electro mechanical systems
OSP	organic solderability preservative
SMD	surface mount device
TAB	tape automated bonding
WLP	wafer level package

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